

L Number	Hits	Search Text	DB	Time stamp
1	123	(accelerometer or sens\$4 or detect\$4) same (vibrat\$4 or displacement or acceleration or mov\$6) same (semiconductor or chip or substrate or ic) with (first or second or two or both) near3 (surface or side) same (align\$6 or misalign\$6)	USPAT; US-PGPUB	2004/07/25 13:38
2	0	73/\$.ccls.	USPAT; US-PGPUB	2004/07/25 13:39
3	116280	73/\$.ccls.	USPAT; US-PGPUB	2004/07/25 13:39
4	19	((accelerometer or sens\$4 or detect\$4) same (vibrat\$4 or displacement or acceleration or mov\$6) same (semiconductor or chip or substrate or ic) with (first or second or two or both) near3 (surface or side) same (align\$6 or misalign\$6)) and 73/\$.ccls.	USPAT; US-PGPUB	2004/07/25 13:39
-	0	(acceleration or vibrat\$4) same chip near3 misalignment same film same (thermosetting or thermoplastic) near3 film	USPAT; US-PGPUB	2004/07/25 13:34
-	0	(acceleration or vibrat\$4) same chip near3 misalignment same film same (thermosetting or thermoplastic) near3 resin	USPAT; US-PGPUB	2004/07/25 12:18
-	1	(acceleration or vibrat\$4) same chip near3 misalignment same film	USPAT; US-PGPUB	2004/07/25 12:18
-	1	(acceleration or vibrat\$4) same chip near3 misalignment same (adhesive or thermosetting or thermoplastic)	USPAT; US-PGPUB	2004/07/25 12:19
-	4	(acceleration or vibrat\$4) same chip near3 misalignment same substrate	USPAT; US-PGPUB	2004/07/25 12:48
-	0	(force or excit\$4 or vibrat\$4) same (acceleration or displacement) same (chip or "semiconductor device") near3 misalignment same substrate same adhesive near3 (polyimide or acrylic) with resin	USPAT; US-PGPUB	2004/07/25 12:54
-	1	(force or excit\$4 or vibrat\$4) same (acceleration or displacement) same (chip or "semiconductor device") near3 misalignment same substrate same adhesive	USPAT; US-PGPUB	2004/07/25 13:04
-	1	5843251.pn.	USPAT; US-PGPUB	2004/07/25 13:14
-	1	6151966.pn.	USPAT; US-PGPUB	2004/07/25 13:18
-	1	6133637.pn.	USPAT; US-PGPUB	2004/07/25 13:18